



P R O S P E C T U S



BCT TECHNOLOGY BERHAD

(Company No. 668945-P)
(Incorporated in Malaysia under the Companies Act, 1965)

BCT TECHNOLOGY BERHAD
(Company No. 668945-P)

BCT TECHNOLOGY BERHAD (668945-P)

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I PUBLIC ISSUE OF 12,200,000 NEW ORDINARY SHARES OF RM0.10 EACH AT AN ISSUE PRICE OF RM1.23 PER ORDINARY SHARE PAYABLE IN FULL ON APPLICATION COMPRISING:

- 10,000,000 NEW ORDINARY SHARES OF RM0.10 EACH AVAILABLE FOR PLACEMENT TO SELECTED INVESTORS;
- 1,000,000 NEW ORDINARY SHARES OF RM0.10 EACH AVAILABLE FOR APPLICATION BY THE PUBLIC;
- 1,200,000 NEW ORDINARY SHARES OF RM0.10 EACH AVAILABLE FOR APPLICATION BY THE DIRECTORS, ELIGIBLE PERSONS AND BUSINESS ASSOCIATES OF BCT TECHNOLOGY BERHAD AND ITS SUBSIDIARIES; AND

II BONUS ISSUE OF 60,980,000 NEW ORDINARY SHARES OF RM0.10 EACH TO BE ISSUED TO ALL EXISTING SHAREHOLDERS OF BCT TECHNOLOGY BERHAD ON THE BASIS OF ONE (1) NEW ORDINARY SHARE OF RM0.10 EACH FOR EVERY ONE (1) EXISTING ORDINARY SHARE OF RM0.10 EACH HELD AFTER THE PUBLIC ISSUE WHICH WILL BE COMPLETED PRIOR TO THE LISTING

IN CONJUNCTION WITH ITS LISTING ON THE MESDAQ MARKET OF BURSA MALAYSIA SECURITIES BERHAD

You are to take note that the Bonus Issue will be implemented after the Public Issue but immediately before the official quotation of our entire enlarged issued and paid-up share capital on the MESDAQ Market. Based on the issue price of RM1.23 per ordinary share, the theoretical ex-bonus price will be RM0.615 per ordinary share.

Adviser, Sponsor, Underwriter and Placement Agent



Southern Investment Bank Berhad (140003-M)

FOR INFORMATION CONCERNING CERTAIN RISK FACTORS WHICH SHOULD BE CONSIDERED BY PROSPECTIVE INVESTORS, SEE "RISK FACTORS" AS SET OUT IN SECTION 4 HEREOF

INVESTORS ARE ADVISED TO NOTE THAT COMPANIES LISTED ON THE MESDAQ MARKET MAY BE OF HIGH INVESTMENT RISK

This Prospectus is dated 26 June 2006

This Prospectus has been seen and approved by the Directors and Promoters of BCT Technology Berhad (BCT Tech or the Company). They collectively and individually accept full responsibility for the accuracy of the information in this Prospectus and confirm, having made all reasonable enquiries, that to the best of their knowledge and belief, there are no false or misleading statement or other facts the omission of which would make any statement in this Prospectus false or misleading.

The Directors hereby accept full responsibility for the profit forecast included in this Prospectus and confirm that the profit forecast has been prepared based on assumptions made.

Southern Investment Bank Berhad, being the Adviser, Sponsor, Underwriter and Placement Agent acknowledges that, based on all available information, and to the best of its knowledge and belief, this Prospectus constitutes a full and true disclosure of all material facts concerning the Public Issue and is satisfied that the profit forecast (for which the Directors of BCT Tech are fully responsible), prepared for inclusion in this Prospectus have been stated by the Directors after due and careful enquiry and have been duly reviewed by the Reporting Accountants.

The Securities Commission (SC) has approved the issue, offer or invitation in respect of the Public Issue and that the approval shall not be taken to indicate that the SC recommends the Public Issue.

The SC shall not be liable for any non-disclosure on the part of BCT Tech and takes no responsibility for the contents of this Prospectus, makes no representation as to its accuracy or completeness and expressly disclaims any liability whatsoever for any loss howsoever arising from or in reliance upon the whole or any part of the contents of this Prospectus. **INVESTORS SHOULD RELY ON THEIR OWN EVALUATION TO ASSESS THE MERITS AND RISKS OF THE INVESTMENT. IN CONSIDERING THE INVESTMENT, INVESTORS WHO ARE IN DOUBT AS TO THE ACTION TO BE TAKEN SHOULD CONSULT THEIR STOCKBROKER, BANK MANAGER, SOLICITOR, ACCOUNTANT OR OTHER PROFESSIONAL ADVISER IMMEDIATELY.**

Admission to the Official List of Bursa Malaysia Securities Berhad (Bursa Securities) is not to be taken as an indication of the merits of the invitation, corporation or of its securities.

A copy of this Prospectus has been registered with the SC. A copy of this Prospectus, together with the form of application, has also been lodged with the Registrar of Companies who takes no responsibility for its contents. Investors are advised to note that recourse for false and misleading statements or acts made in connection with this Prospectus is directly available through Sections 57, 58 and 153 of the *Securities Commission Act 1993*.

CHARACTERISTICS OF THE MESDAQ MARKET OF BURSA SECURITIES— Investors should be aware that MESDAQ is a distinct market from the Main and Second Boards of Bursa Securities in many respects. In particular, companies listed on the MESDAQ Market are subject to different quantitative and qualitative requirements, which have been primarily designed to accommodate high-growth and/or technology companies. Companies that are listed on MESDAQ MARKET may have a limited operating history or may not have any profit track record prior to the listing. As such, these companies may be of high investment risk. The regulatory philosophy underlying the MESDAQ Market is that the market should be allowed to determine the merits of the securities/instruments in a particular company. Hence, as with all investments, prospective investors should be aware of all potential risks in investing in such companies and should make the decision to invest after due and careful consideration by referring to, amongst others, this Prospectus, latest financial statements and corporate announcements. In this respect, advice from a securities professional/adviser is strongly recommended.

You can view and download this Prospectus from Bursa Securities' website at www.bursamalaysia.com.

INDICATIVE TIMETABLE

The indicative timing of events leading up to the listing of and quotation for our entire enlarged issued and paid-up share capital on the MESDAQ Market, is set out below:

Events	Date/Day
Opening of Application for our Public Issue	26 June 2006 - Monday
Closing of Application of our Public Issue	3 July 2006 - Monday
Balloting date for our Public Issue	5 July 2006 - Wednesday
Allotment date of our Public Issue Shares to successful Applicants	7 July 2006 - Friday
Listing date on the MESDAQ Market	13 July 2006 - Thursday

Note:

Application for our Public Issue will remain open from 10.00 a.m. on 26 June 2006 to 5.00 p.m. on 3 July 2006 or for such further period or periods as our Directors and/or Promoters in their absolute discretion may decide in consultation with the Underwriter. Should the closing date of the Application for our Public Issue be extended, the tentative dates for the balloting, despatch of Notices of Allotment and listing of our entire enlarged issued and paid-up share capital on the MESDAQ Market would be extended accordingly. We will not accept late Applications for our Public Issue after the closing date, or the extended closing date, as the case maybe.

If our Directors and Underwriter decide to extend the closing date of the Application, appropriate press releases will be made to the local news agencies and will be advertised in a daily Bahasa Malaysia newspaper and a daily English newspaper prior to the original closing date of the Application.

This timetable is indicative and is subject to changes, which may be necessary to facilitate implementation procedures.

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ABBREVIATIONS

All references to “we”, “us”, “our” and “ourselves” are to our company, BCT Technology Berhad and our subsidiaries. Unless the context otherwise requires, references to “Management” are to our Directors and key management personnel as at the date of this Prospectus, and statements as to our beliefs, expectations, estimates and opinions are those of our Management.

In this Prospectus, the words and phrases below, unless the context otherwise requires, shall bear the meanings assigned next to them:

Abbreviations	Meanings
Companies/Persons	
BCSM or our Malaysia subsidiary	Blue-Chips Semiconductors (M) Sdn Bhd
BCSPL	Bluechips Semiconductors Private Limited, an associate company of BCT which had been disposed of on 20 December 2004
BCT or our Singapore subsidiary	BlueChips Technology Pte Ltd
BCT Tech or our Holding Company	BCT Technology Berhad
BCTHK or our Hong Kong subsidiary	Bluechips Technology (HK) Limited
BCT Tech Group or our Group	BCT Tech and its subsidiaries, namely BCT, BCSM and BCTHK
KMPSB	Kumpulan Modal Perdana Sdn Bhd
RCPS Subscribers	KMPSB, Annie Loo Yean Lay, Low Teck Seng and Goh Phaik Lynn, collectively
Vendors	Wong Nga Chung, Chong Yew Peng, Ho Monica Wai Mei, Lee Woon Wo, Lam Kam Kwai, Leung Po Chuen, Chia Cher Kiang, Lee Wai Kuen, Thomrose Holdings (BVI) Limited, Tang Pen San and Khairil Anuar bin Abdullah, collectively
Restructuring Scheme	
Acquisition	Acquisition by us of the entire issued and paid-up share capital of our Singapore subsidiary of SGD1,343,483 comprising 1,343,483 BCT Shares for a purchase consideration of RM350,000 satisfied by the issuance of 3,500,000 new Shares at an issue price of RM0.10 per Share
Bonus Issue I	Bonus issue of 39,767,422 new Shares to our existing shareholders except for the new Shares issued pursuant to the RCPS Conversion to the RCPS Subscribers, on the basis of approximately 10.52 new Shares for every one (1) existing Share held
RCPS Conversion	Conversion of our BCT Tech RCPS into Shares upon obtaining the approvals from the relevant authorities based on the conversion price stipulated in the Subscription Agreement
RCPS Issue	Issue of 4,500,000 new BCT Tech RCPS at the issue price of RM1.00 per BCT Tech RCPS to the RCPS Subscribers
Restructuring Scheme	Acquisition, RCPS Issue, ESOS I, RCPS Conversion and Bonus Issue I, collectively
Share Sale Agreement	The agreement dated 18 November 2004 for the sale and purchase of the Sale Shares entered into between the Vendors and us
Subscription Agreement	The agreement entered on 18 November 2004 between the RCPS Subscribers and us pursuant to which the RCPS Subscribers had agreed to subscribe for and we had agreed to issue 4,500,000 BCT Tech RCPS at an issue price of RM1.00 per BCT Tech RCPS

ABBREVIATIONS

Abbreviations	Meanings
Listing Scheme	
Placement/Public Issue Price	Placement/Public Issue price of RM1.23 per Share
Bonus Issue II	Bonus issue of 60,980,000 new Shares to our existing shareholders on the basis of one (1) new Share for every one (1) existing Share held after the Public Issue
Listing	The admission to the Official List of the MESDAQ Market and the listing of and quotation for our entire enlarged issued and paid-up share capital on the MESDAQ Market as set out below: <ul style="list-style-type: none"> ▪ RM12,196,000 comprising 121,960,000 new Shares; and ▪ Up to RM1,829,400 comprising 18,294,000 new Shares pursuant to the ESOS II.
Listing Scheme	Public Issue, Bonus Issue II, ESOS II and Listing, collectively
Pink Form Share Allocation Scheme	Issue of 1,200,000 new Shares to our directors, eligible employees and business associates pursuant to the Public Issue
Public Issue	Public issue of 12,200,000 new Shares at the Public Issue Price of RM1.23 per Share payable in full on application
Placement	Placement of 10,000,000 new Shares to selected investors pursuant to the Public Issue at the Placement Price
ESOS	
Bye-Laws	Collectively the ESOS I and ESOS II Bye-Laws, which set out the terms and conditions of the ESOS I and ESOS II and as amended from time to time in accordance with the respective terms and conditions
ESOS I	Our employee share option scheme established and completed pursuant to the Bye-Laws for the granting of Options prior to our Listing
ESOS II	Our employee share option scheme established pursuant to the Bye-Laws for the granting of Options after obtaining the approval-in-principle of Bursa Securities for our Listing
Eligible Person	Our employee or director who is eligible to participate in the ESOS I and ESOS II in accordance with the provisions of the Bye-Laws
ESOS or Schemes	Collectively the ESOS I and ESOS II established pursuant to the Bye-Laws for the granting of Options of up to: <ul style="list-style-type: none"> - 15% of the issued and paid-up share capital of our Holding Company at any one time during the existence of the ESOS I; and - 15% of the issued and paid-up share capital of our Holding Company at any one time during the existence of the ESOS II, to Selected Persons who will upon their acceptance, entitle them to subscribe for our new Shares in accordance with the Bye-Laws
ESOS Committee	The committee comprising such persons as may be appointed by the Board which from time to time, in accordance with the Bye-Laws to administer the Schemes

ABBREVIATIONS

Abbreviations	Meanings
Grantee	A Selected Person who has accepted the Offer made by the ESOS Committee in accordance with the Bye-Laws
Offer	An offer made in writing by the ESOS Committee to a Selected Person in the manner set out in the Bye-Laws
Option(s)	The right of a Grantee to subscribe for our Shares pursuant to the contract constituted by acceptance in the manner indicated in the Bye-Laws of any Offer made in accordance with the terms of the Schemes and where the context so requires, means any part(s) of the Option(s) as shall remain unexercised
Selected Person(s)	An Eligible Person who has been selected by the ESOS Committee to participate in the Schemes and to whom an Offer has been made in writing by the ESOS Committee in accordance with the Bye-Laws
Trust Deed	The trust deed executed between Mayban Trustees Berhad and our Holding Company dated 15 April 2005 in relation to the ESOS I, Bonus Issue I and Bonus Issue II
Trustee	Mayban Trustees Berhad (Company No. 5004-P)
Securities	
BCT Share(s)	Ordinary share(s) of SGD1.00 each in our Singapore subsidiary
Share(s)	Ordinary share(s) of RM0.10 each in our Holding Company
BCT Tech RCPS or RCPS	Redeemable convertible preference shares of RM0.10 each in our Holding Company
Bonus Issue I Shares	39,767,422 new Shares issued pursuant to the Bonus Issue I
Bonus Issue II Shares	60,980,000 new Shares to be issued pursuant to the Bonus Issue II
Consideration Shares	3,500,000 new Shares issued pursuant to the Acquisition
Sale Shares	1,343,483 ordinary shares of SGD1.00 each in our Singapore subsidiary, representing 100% of the issued and paid-up share capital of our Singapore subsidiary
Public Issue Shares	12,200,000 new Shares to be issued pursuant to the Public Issue, which are subject to the terms and conditions of this Prospectus
Authorities/ Regulations	
Act	Companies Act, 1965, as amended from time to time and any re-enactment thereof
ADA	Authorised Depository Agent
ADA Code	ADA (Broker Code)
BNM	Bank Negara Malaysia
Bursa Securities	Bursa Malaysia Securities Berhad
Bursa Depository or Depository	Bursa Malaysia Depository Sdn Bhd
Bursa Depository Rules	Rules of Bursa Depository
Central Depositories Act	Securities Industry (Central Depositories) Act, 1991 as amended from time to time and any re-enactment thereof
FIC	Foreign Investment Committee

ABBREVIATIONS

Abbreviations

FIC Guidelines	Guidelines on the Acquisition of Assets, Mergers and Take-overs issued by the FIC
MDC	Multimedia Development Corporation Sdn Bhd
MESDAQ	Malaysian Exchange of Securities Dealing and Automated Quotation Berhad
MESDAQ Market	MESDAQ Market of Bursa Securities
MMLR	Listing Requirements of Bursa Securities for the MESDAQ Market
MITI	Ministry of International Trade and Industry
MSC	Multimedia Super Corridor
OFFICIAL LIST	List specifying all securities which have been admitted for listing on Bursa Securities and not removed
ROC	Registrar of Companies, Malaysia
SC	Securities Commission
SC Guidelines	Policies and Guidelines on Issue/Offer of Securities of the SC

Adviser/Sponsor

SIBB	Southern Investment Bank Berhad
Underwriter and Placement Agent	SIBB

Financial Terms

EI	Extraordinary items
EPS	Earnings per share
GP	Gross profits
LBT	Loss before tax
LPS	Loss per share
MI	Minority interest
NTA	Net tangible assets
PAT	Profit after taxation
PBT	Profit before taxation
PE multiple	Price earnings multiple

Others

Applicant(s)	Applicant(s) making the Application
Application	Application for the Public Issue by way of Application Form or an Electronic Share Application
Application Form	A printed form for purpose of applying for the Public Issue Shares
ASEAN	The Association of South East Asian Nations
BCT Tech Board	Board of Directors of BCT Tech
Board	Board of Directors
Cadence	Cadence Design Systems (Ireland) Limited
CDS	Central Depository System
CEO	Chief Executive Officer

ABBREVIATIONS

Abbreviations

Abbreviations	Meanings
Computime	Computime Ltd
EGM	Extraordinary General Meeting
HKD	Hong Kong Dollar
IMR	Independent Market Researcher i.e. InfoCredit D&B (Malaysia) Sdn Bhd
IMR Report	Independent Market Researcher Report prepared by IMR dated 1 April 2006
Latest Practicable Date	31 March 2006, being the latest practicable date for purposes of due diligence, prior to the issuance of this Prospectus
NDP	National Development Policy
p.a.	per annum
R&D	Research and development
RM and sen	Ringgit Malaysia and sen respectively
SGD	Singapore Dollar
USA or US	United States of America
USD	United States Dollar

Technical Terms

μ	(Greek letter mu) meaning micro or factor of 10^{-6} or a millionth part
μm	Micrometer or a millionth part of a meter
μS	Micro second
A	Amperes
mA	milli-Amperes
W	Watt
AC	Alternating Current: The common form of electricity from power plant to home/office
ADC	<p>Analog-to-Digital Converter: Analog-to-digital conversion is an electronic process in which a continuously variable (analog) signal is changed, without altering its essential content, into a multi-level (digital) signal.</p> <p>The input to an ADC consists of a voltage that varies among a theoretically infinite number of values. Examples are sine waves, the waveforms representing human speech, and the signals from a conventional television camera. The output of the ADC, in contrast, has defined levels or states. The number of states is almost always a power of two – that is, 2, 4, 8 and 16. The simplest digital signals have only two (2) states, and are called binary. All whole numbers can be represented in binary form as strings of ones and zeros.</p>

ABBREVIATIONS

Abbreviations	Meanings
Analog	Analog describes any fluctuating, evolving, or continually changing process. An analog signal can be represented as a series of sine waves. The term originated because the modulation of the carrier wave is analogous to the fluctuations of the human voice or other sound that is being transmitted.
ASSP	Application-Specific Standard Product: A Chip product with standard specifications which can be used for various target applications
ASIC	Application-Specific Integrated Circuit: A Chip custom designed specifically for a particular application i.e. for one end product or a closely related family of end-products
Bare Die or Die	One individual Chip cut from a wafer before being packaged
bit	Abbreviation for binary digit
Bright LED Drivers	A driver chip that switches on and off a bright LED light
Channel	The semiconductor path on which current flows
Charge Pump	An electronic circuit which uses capacitors to store and transfer energy to the output, often stepping the voltage up or down. Charge is transferred from one capacitor to another under the control of a regulator and switching circuit
Chip or IC	A chip or microchip is a unit of a completely functional packaged electronic circuitry (usually called an integrated circuit) that is manufactured from a material such as silicon
CMOS	Complementary metal-oxide-semiconductor. A fabrication process that incorporates n-channel and p-channel CMOS transistors within the same Silicon substrate. Currently, this is the most commonly used Chip fabrication process technology and is one of the latest fabrication techniques to use metal oxide semiconductor transistors
CPU	Central Processing Unit: The computing part of the computer. Also called the "processor," it is made up of the control unit and arithmetic logic unit. Today, the CPUs of almost all computers are contained on a single Chip. The CPU, clock and main memory make up a computer. A complete computer system requires the addition of control units, input, output and storage devices and an operating system.
Dice or Dies	Plural term for Bare Die or Die
Digital	Digital describes electronic technology that generates, stores, and processes data in terms of two (2) states: positive and non-positive. Positive is expressed or represented by the number 1 and non-positive by the number 0. Thus, data transmitted or stored with digital technology is expressed as a string of 0's and 1's. Each of these state digits is referred to as a bit (and a string of bits that a computer can address individually as a group is a byte)
DC	Direct Current: An electrical current that travels in one direction and used within the computer's electronic circuits

ABBREVIATIONS

Abbreviations**Meanings**

DIP	Dual In-line Package: A common rectangular Chip housing with leads (pins) on both long sides. Tiny wires bond the Chip to metal leads that wind their way down into spider-like feet that are inserted into a socket or are soldered onto the board. The DIP package is commonly used to hold small Chips, such as main memory, cache memory, AD and Digital to Analog converters
Driver	A program that controls a device
DSP	Digital Signal Processor: A special-purpose CPU used for digital signal processing. It provides ultra-fast instruction sequences, such as shift and add, and multiply and add, which are commonly used in math-intensive signal processing applications. DSP Chips are widely used in a myriad of devices, including sound cards, fax machines, modems, cellular phones, high-capacity hard disks and digital TVs
DVD	Digital Versatile Disc
EDA	Electronic Design Automation: A large collection of software tools that enhance and aid in the design of a Chip
EEPROM	Electrically Erasable Programmable ROM: A rewritable memory Chip that retains its content even when the power is turned off. Unlike EPROMs, which have to be placed under UV light for erasure, EEPROMs are electrically erased in place by exposing it to an electrical charge.
EPROM	Erasable Programmable ROM: A rewritable memory Chip that retains its content until it is exposed to UV light
EMS	Electronic Manufacturing Services i.e. contract manufacturing companies
Fabless	Without having a fabrication manufacturing facility
Foundry	Contract wafer fabrication facility
FPGA	Field-Programmable Gate Array: A specially made digital semiconductor often used for prototyping. With an FPGA, a design engineer is able to program electrical connections on site for a specific application (for example a device for a sound/video card), without high costs to have the Chip manufactured in mass quantities
Gate	The structure used to control output current (i.e. flow of carriers in the channel) in the transistor
Graphic Chip	A computer processor Chip that specifically produces computer image to be displayed on computer screen
HDL	Hardware Description Language: A synthetic computer-based language used for the formal description of electronic circuits. A HDL can describe a circuit's operation, its design, and a set of tests to verify circuit operation through simulation. The two most popular digital HDLs are VHDL and Verilog. An analog HDL called AHDL is under development by many vendors. HDLs make it easier to develop very large designs through formal software engineering methods that define ways to divide a large team project into smaller pieces that can be implemented by individual team members.

ABBREVIATIONS

Abbreviations	Meanings
High Efficiency Power Supply	Devices which promote high output efficient power conversion
HSPICE	It is a commercial version of the SPICE program. Depending on the vendor, there are several commercially available versions such as PSPICE, SPECTRE as well as HSPICE.
IP	Trade marks, trade names, copyrights, patents, confidential information or other industrial or intellectual property rights all in relation to the business of our Group and subsisting in respect of the business of our Group or the marketing of the relevant products by our Group including designs of the samples, patterns, instructions, books, technical pamphlets, catalogues, labels, advertising and promotional material, specifications, any printed material and application for any of the foregoing which belong to our Group
IP Core	Intellectual Property Core: A broad category of materials that are recognised as proprietary to an organisation. In the electronics field, IP Core refers to specific portions of a Chip or "building blocks" that can be proprietary and/or patented designs of a particular company. These IP "blocks" or cores can then be sold to customers as commodity parts for new designs
Layout	The process of planning and implementing the location of devices within a Chip design
Layout Diagram	Layout Diagram refers to the design of the geometric-physical structure of a Chip
LCD	Liquid Crystal Display
LED	Light Emitting Diode
Mask	A glass plate with a pattern of transparent and opaque areas used to create patterns on wafers. "Mask" is commonly used to refer to a plate that has a pattern on a whole wafer at one time, as compared to a reticle, where a glass plate can contain the pattern for one or more Dice but is not large enough to transfer a wafer-sized pattern all at once.
MCU	Micro Controller Unit: A computer on a single Chip
Mixed-Signal	The combination of Analog and Digital circuitry in a single semiconductor
MOS	Metal-oxide-semiconductor
MOSFET	Metal-oxide-semiconductor Field Effect Transistor: A field effect transistor with an oxide coating between the Gate and the Channel. MOSFET is a type of transistor in which charge carriers, such as electrons, flow along Channels. The width of the Channel, which determines how well the device conducts, is controlled by an electrode called the Gate, which is separated from the Channel by a thin layer of oxide insulation.
MHz	Mega Hz (1,000,000 Hz)
ODM	Original Design Manufacturer
OEM	Original Equipment Manufacturer
OLED	Organic LED: It is a thin-film, light-emitting device that typically consists of a series of organic layers between two electrical contacts (electrodes). OLEDs are monolithic devices because each layer is deposited on the other, creating a single unit.

ABBREVIATIONS

Abbreviations	Meanings
Package	The sealed, protective container that houses an electronic component or Bare Die. External terminals provide electrical access to the components inside. Packages provide for power and signal distribution, power dissipation, and protection of the circuits.
PC	Personal computer
PCB	Printed circuit board
PCBA	Printed circuit board assembly, a process to assemble all the components onto a printed circuit board
PDA	Personal Digital Assistant
PDIP	Plastic Dual-In-Line Package. A package having two rows of leads extending at right angles from the base and having standard spacing between leads and between rows of leads. The leads are made from metal materials and then encapsulated by plastic compound to form the package.
Precision Linear	Basic Analog circuitry which requires precision function, i.e. band gap reference circuits, filters, operation amplifier
PWM	Pulse Width Modulation
QFN	Quad Flat No-Lead: 3 mm sq Package type
Quasi-ZVS	Near ZVS
RF	Radio Frequency: High frequency electrical signals that can be a source of electromagnetic wave radiation
ROM	Read-only-memory
Schematic	A graphical representation of an electronic circuit. Until the 1980s, schematics were really the only representation system used to describe circuits. However, with the advent of HDLs and an explosion in circuit complexity, schematics are becoming less important as a representation tool.
Schematic Entry	The process of drawing a schematic using EDA tools. When done with paper and pencil, schematic entry is called schematic drafting or schematic drawing.
Semiconductor	An element with an electrical resistance within the range of an insulator and a conductor; a semiconductor can conduct or block the flow of electric current depending on the direction and magnitude of applied electrical biases
Silicon	The basic material used to make computer Chips, transistors, silicon diodes and other electronic circuits and switching devices as its atomic structure makes the element an ideal Semiconductor
Simulation	The process of using software to model an electronic system
SMPS	Switching-Mode Power Supply: A power supply that provides the power supply function through low loss components such as capacitors, inductors and transformers - and the use of switches that are in one of two states, on or off. The advantage of a SMPS is that the switch dissipates very little power in either of these two states and power conversion can be accomplished with minimal power loss, which equates to high efficiency.

ABBREVIATIONS

Abbreviations	Meanings
SOIC	Small-Outline Integrated Circuit: A carrier which occupies an area about 30% - 50% less than an equivalent DIP, with a typical thickness that is 70% less. This package has "gull wing" leads protruding from the two long sides and a lead spacing of 0.050 inches.
Solid State	Refers to the electronic properties of crystalline (generally Semiconductor) material-as opposed to vacuum and gas-filled tubes. Solid State devices involve the interaction of light, heat, magnetic field, and electric currents in crystalline materials
SPICE	Simulation Program with Integrated Circuit Emphasis: One of the pioneer Analog Simulation programs developed at the University of California at Berkeley in the early 1970s.
Tapeout	A step of converting the Layout design Mask data to the standard data format file. This file is then sent to the fabrication facility. Then, a set of Masks is generated.
Transistor	A device composed of Semiconductor material that amplifies a signal or opens or closes a circuit
UV	Ultraviolet Light
V	Voltage: The force applied between two points causing charged particles (and therefore, current) to flow
VCD	Video Compact Disc
VFD	Vacuum Fluorescence Display
VGA	Video Graphics Array: The video display standard for the PC. VGA uses an analog monitor, and the VGA circuits, either on the display adapter or motherboard, convert the digital signals in the computer to analog for the analog monitor
VLSI	Very Large Scale Integration: Between 100,000 and one million transistors on a Chip
VRM	Voltage Regulator Module
VRM Controller	Voltage Regulator Module Controller
Wafer	A thin, round, flat piece of semiconductor material, typically Silicon, from which Chips are made
Watt	A unit of energy which is used to measure power used or consumed. A kilowatt (KW) equals 1,000 watts
ZVS	Zero Volt Switching: The synchronising of the operation of semiconductor switches in (resonant) power converters with the natural voltage zero crossing in the converter's power circuit, results in a near lossless switch used to produce high efficiency power supply

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